

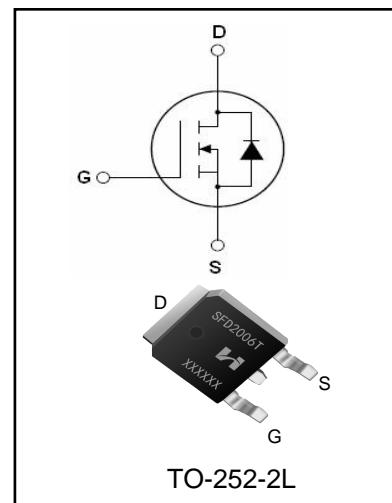
## 60A, 20V N-CHANNEL MOSFET

### GENERAL DESCRIPTION

The SFD2006T uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications.

### FEATURES

- ◆ 60A, 20V,  $R_{DS(on)(typ.)}=5.6\text{m}\Omega$  @  $V_{GS}=4.5\text{V}$
- ◆ Excellent package for good heat dissipation
- ◆ Fully characterized avalanche voltage and current
- ◆ Good stability and uniformity with high EAS
- ◆ High density cell design for ultra low Rdson
- ◆ Special process technology for high ESD capability



### ORDERING INFORMATION

Part No.	Package	Marking	Material	Packing
SFD2006T	TO-252-2L	SFD2006T	Pb free	Reel

### ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ\text{C}$ unless otherwise noted

Characteristics		Symbol	Ratings	Unit
Drain-Source Voltage		$V_{DS}$	20	V
Gate-Source Voltage		$V_{GS}$	$\pm 12$	V
Drain Current	$T_C = 25^\circ\text{C}$	$I_D$	60	A
	$T_C = 100^\circ\text{C}$		42	
Drain Current Pulsed (Note 1)		$I_{DM}$	220	A
Maximum Power Dissipation		$PD$	65	W
Operation Junction Temperature Range		$T_J$	-55~+150	$^\circ\text{C}$
Storage Temperature Range		$T_{stg}$	-55~+150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.82	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	0.48	$^\circ\text{C}/\text{W}$

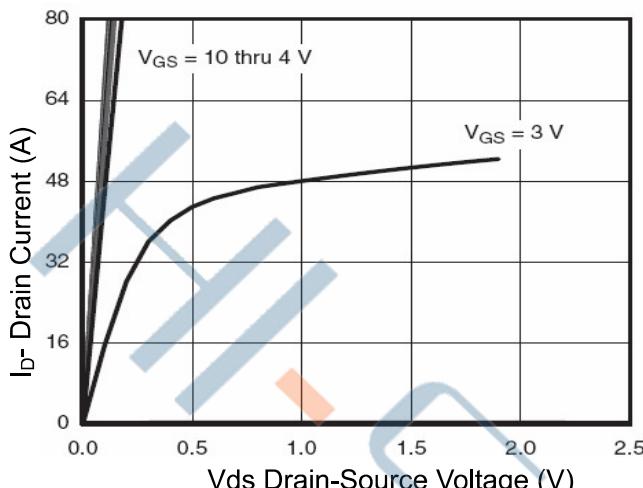
Electrical Characteristics  $T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}$ , $I_D = 250\mu\text{A}$ ,	20	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 16\text{V}$ , $V_{GS} = 0\text{V}$	-	-	10	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current, Forward	$V_{GS} = \pm 12\text{V}$ , $V_{DS} = 0\text{V}$	-	-	$\pm 100$	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 1\text{mA}$	0.5	0.7	1.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 4.5\text{V}$ , $I_D = 20\text{A}$	-	5.6	8.0	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = 10\text{V}$ , $V_{GS} = 0\text{V}$ , $f = 1.0\text{MHz}$	-	1850	-	pF
$C_{oss}$	Output Capacitance		-	473	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	200	-	pF
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 10\text{V}$ , $I_D = 1\text{A}$ , $V_{GS} = 5\text{V}$ RGEN = $3.3\Omega$	-	9.8	-	ns
$t_r$	Turn-On Rise Time		-	20	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	35	-	ns
$t_f$	Turn-Off Fall Time		-	17.5	-	ns
$Q_g$	Total Gate Charge	$V_{DS} = 10\text{V}$ , $I_D = 20.0\text{A}$ , $V_{GS} = 4.5\text{V}$	-	29.3	-	nC
$Q_{gs}$	Gate-Source Charge		-	5.8	-	nC
$Q_{gd}$	Gate-Drain Charge		-	6.3	-	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain-Source Diode Forward Current	$V_{GS} = 0\text{V}$ , $I_s = 2.5\text{A}$ $V_{GS} = 0\text{V}$ , $I_s = 20\text{A}$ , $dI/dt = 100\text{A}/\mu\text{s}$	-	-	60	A
$V_{SD}$	Drain-Source Diode Forward Voltage		-	-	1.2	V
$t_{rr}$	Reverse Recovery Time		-	35	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	29	-	$\mu\text{C}$

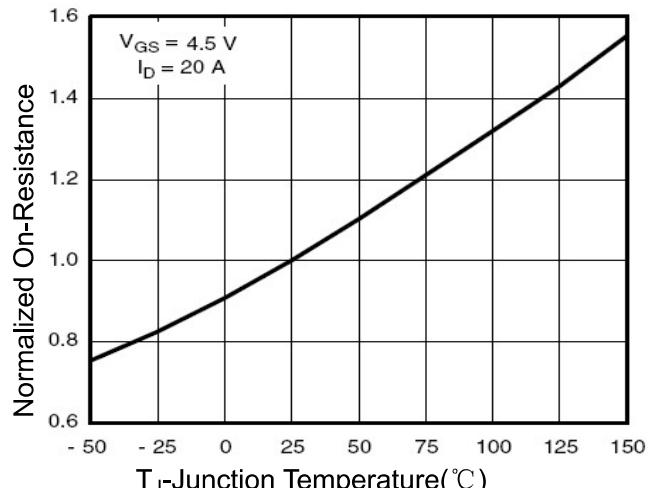
**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5. E<sub>AS</sub> condition :  $T_j=25^\circ\text{C}$ ,  $V_{DD}=10\text{V}$ ,  $V_G=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_g=25\Omega$ .

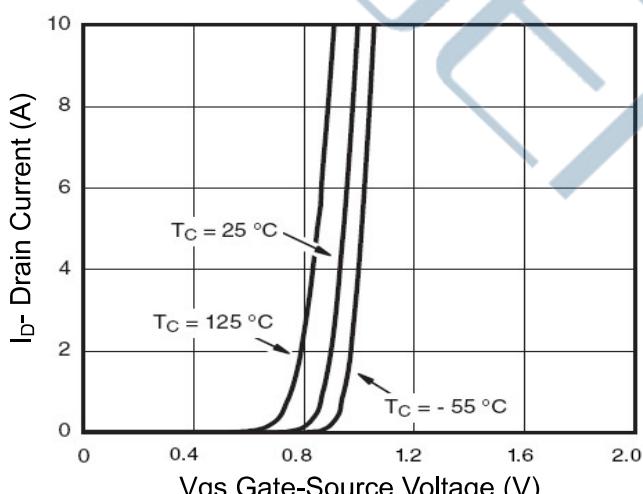
### Typical Electrical and Thermal Characteristics (Curves)



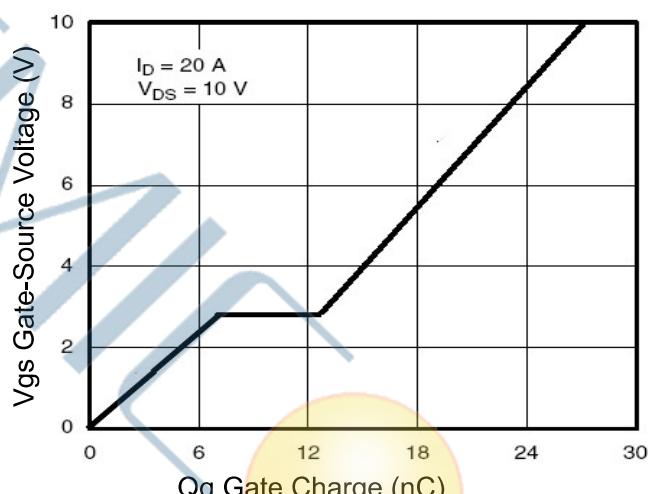
**Figure 1 Output Characteristics**



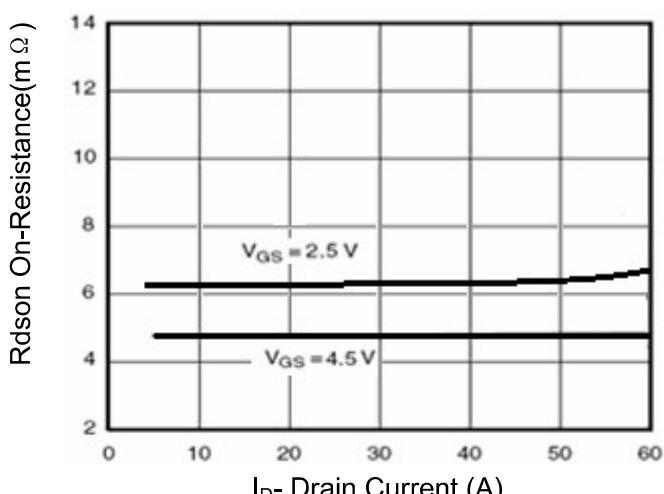
**Figure 4 Rdson-JunctionTemperature**



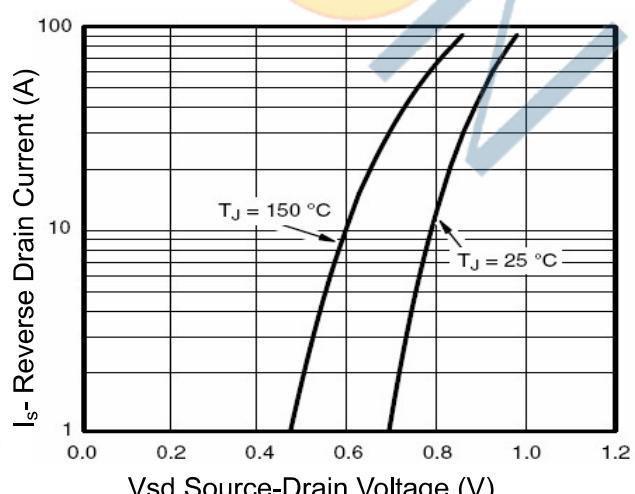
**Figure 2 Transfer Characteristics**



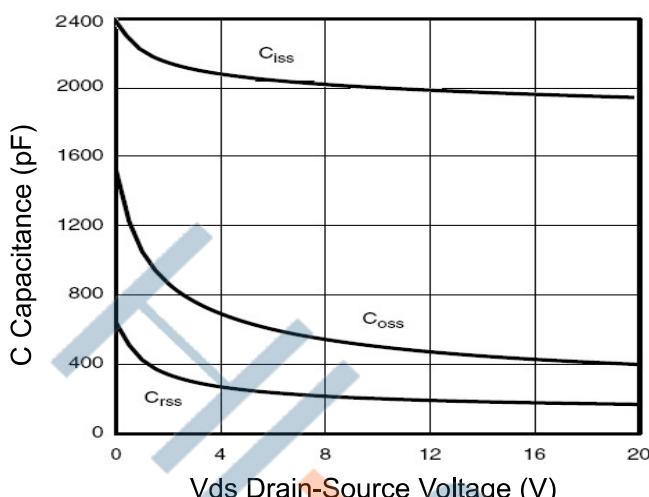
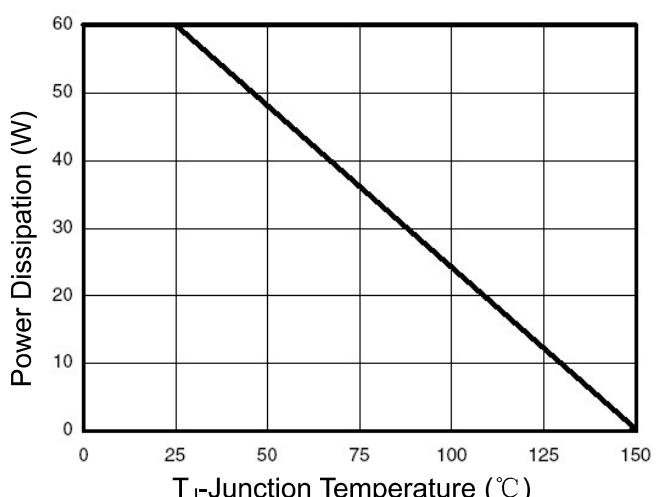
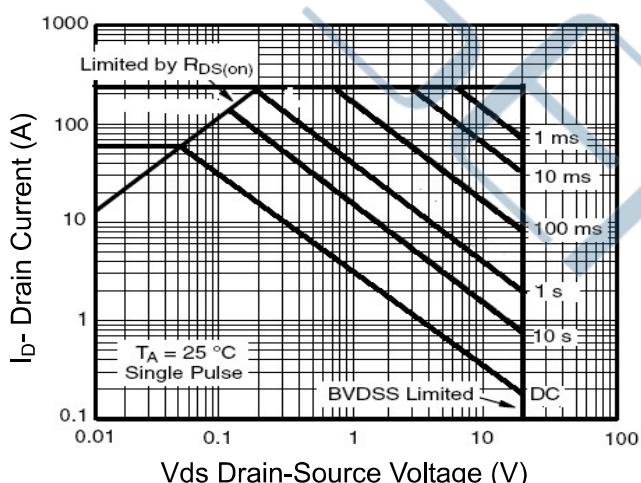
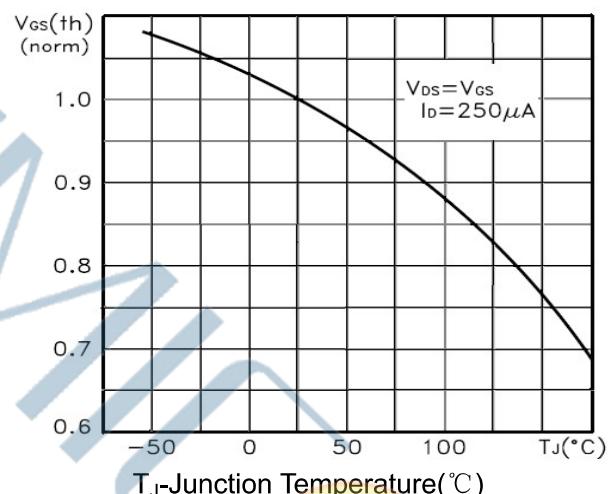
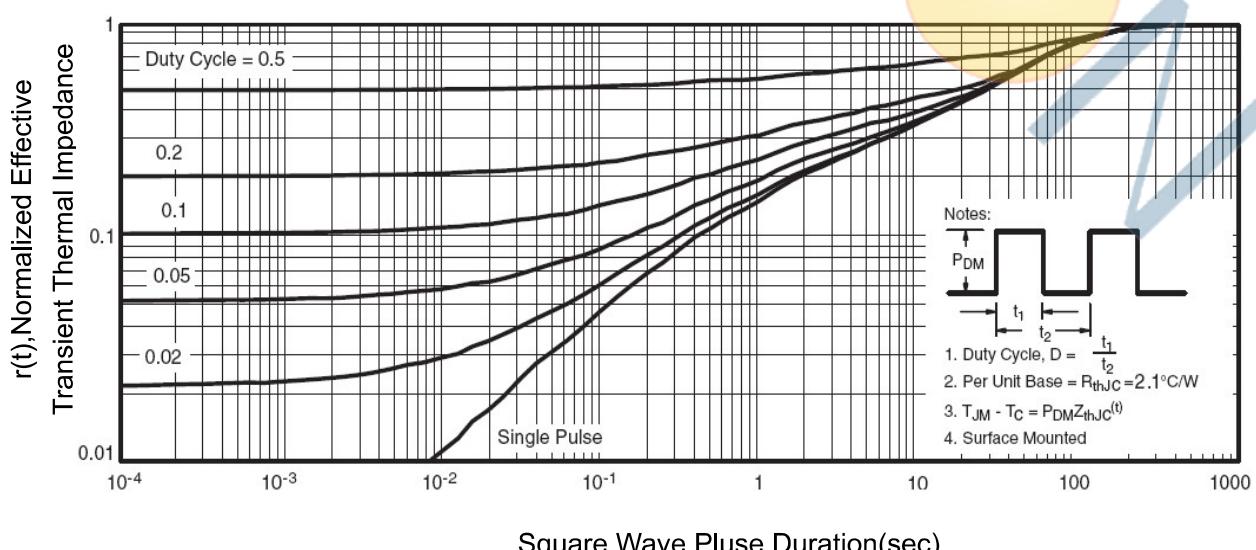
**Figure 5 Gate Charge**

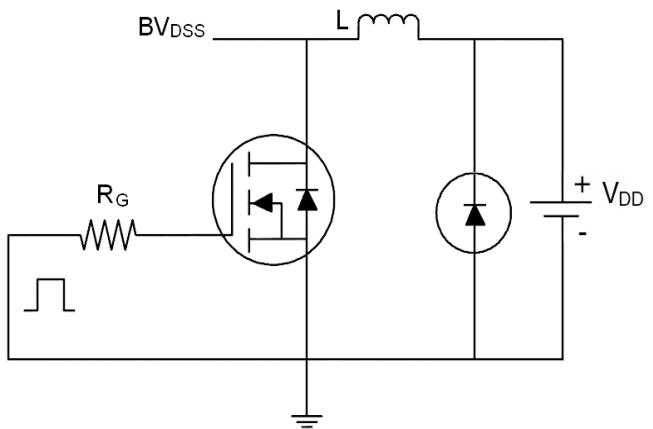
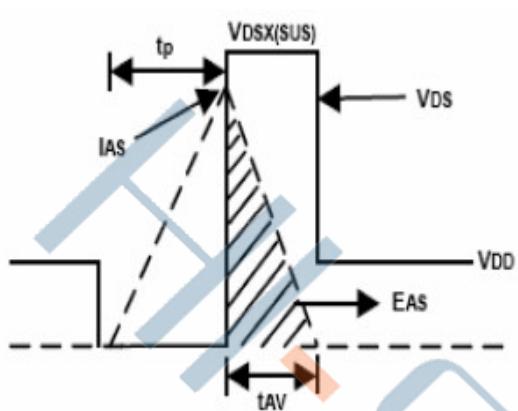
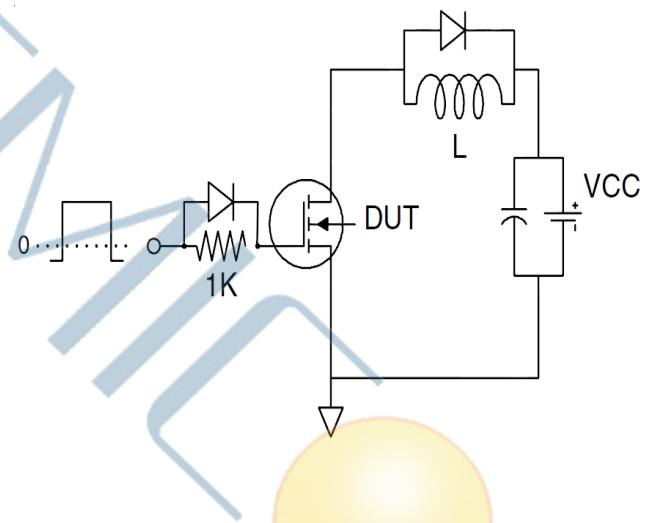
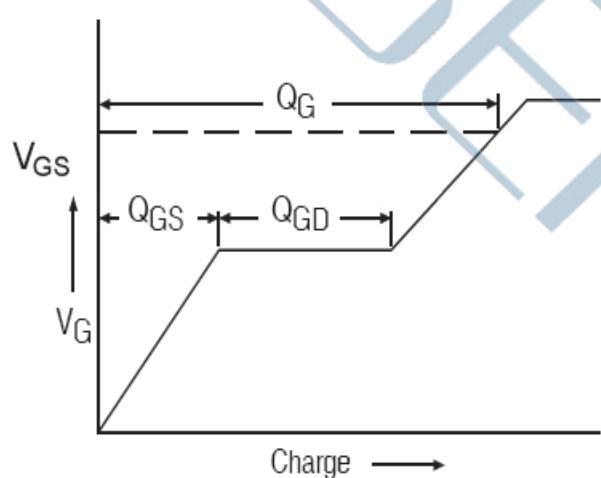


**Figure 3 Rdson- Drain Current**



**Figure 6 Source- Drain Diode Forward**

**Figure 7 Capacitance vs Vds****Figure 9 Power De-rating****Figure 8 Safe Operation Area****Figure 10  $V_{GS(th)}$  vs Junction Temperature****Figure 11 Normalized Maximum Transient Thermal Impedance**

**1) E<sub>AS</sub> Test Circuits****2) Gate Charge Test Circuit:****3) Switch Time Test Circuit:**